

TBBP-A free



MSL Level 1

ROHS-Y

# Approval Sheet

Products	Dielectric Chip Antenna				
Customer	DIOSTECH				
Model		RD-02			
Customer CODE					
Supplier		PARTRON			
Supplier CODE		ACS2450JBARD2			
	By designed	By checked	By approved		
CLIPCOM					
	By designed	By checked	By approved		
PARTRON	with	Strike	例从		
	Research 5 Team	Quality Assurance	Laboratory		
	Chanik.Jeon	Nam-Sik.Min	Byoung-Jun.Yim		
	4 / 14	4 / 14	4 / 14		

2008. 4. 14



22-6 Seokwoo-dong, Hwaseong-si, Gyeonggi-do, Korea 455-300

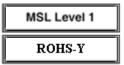
Te I: 82-31-201-7870~6 Fax: 82-31-201-7800 www.partron.co.kr

Ver 1.0 (2008.04.14) 1 /31 Page



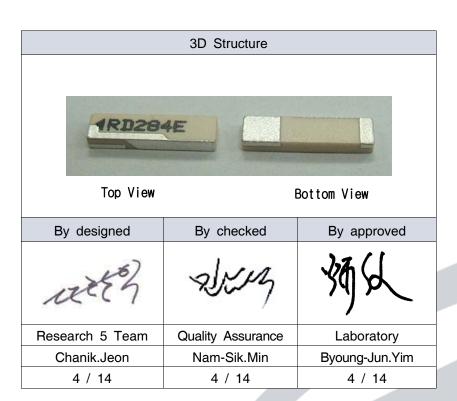






# **SPECIFICATION**

MODEL: ACS2450JBARD2



2008. 4. 14



22-6 Seokwoo-dong, Hwaseong-si, Gyeonggi-do, Korea 455-300

Tel: 82-31-201-7870~6 Fax: 82-31-201-7800 www.partron.co.kr

Ver 1.0 (2008.04.14) 2 /31 Page



## - Contents -

1.	Revision History	4 p
2.	Summary of Parts	5 p
3.	Critical to Quality	5р
4.	Electrical Characteristics	6 p
5.	Measurement Process	11 p
6.	Internal Block Diagram	13 p
7.	Basis Action / Application Note	13 p
8.	Measurement Jig SPEC	14 p
9.	REFLOW PROFILE	15 p
0.	Primary Inspection List	16 p
1.	Reliability Condition	17 p
2.	Mechanical Characteristics	15 p
3.	Structure and Material	17 p
4.	Attention	21 p
5.	Packing	22 p
6.	Process Control	26 p
7.	RoHS Data	29 p



# 1. Revision

Revision No	Originator	Description of changes	Date of changes
Ver 1.0	Chanik.Jeon	Issued	2008.04.14

Ver 1.0 (2008.04.14) 4 /31 Page



#### 2. Summary of Parts

- This product is the internal dielectric chip antenna of radio communication, forms the pattern with Ag paste on the brick of dielectric block and materializes the characteristics

Туре	Only Bulk Ceramic				
Motorial	Dielectric Block	Mg₂SiO₄(Magnesium Silicate)			
Material	Electrode Paste	Ag			
	$W = 2.5 \pm 0.1$				
Size[mm]	L = 10.0±0.1	Ag Paste			
	$T = 1.2 \pm 0.1$	W			
Flatness Level	0.04	T.			
MSL Level	MSL Level 1				
ESD Level	More than 15 KV (HBM CLASS 3B)	Top - Side View Block Bottom Side View			
Version	Revision 1.0				

# 3. Critical to Quality (

- The following list is specified as the emphasis management list and managed.

CTQ ITEM	Specification Reason			
Shape weight, size	Shape weight and size determines the electric block size after plastic and the dielectric block size effects the level of detail for the printing.			
Plastic Size	The size after plastic effects the level of detail for the printing.			
Printing Size	The level of detail for printing size is an essential list of the BT antenna.			

CTF ITEM 🐟	Specification Reason
Single Element measurement SWR	An important Parameter classifying the electrical characteristics.

- require attention for the following list.

ITEM	Content
Keeping	Sealing tightly when keeping for a long time.
Action	Maybe characteristics changes when changing any design.

Ver 1.0 (2008.04.14) 5 /31 Page



# 4. Electrical Characteristics

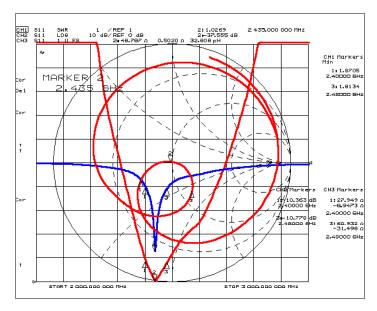
#### 4.1 Set Condition

ITEM				SPEC		
Frequency Range [MHz]				2400 ~ 2485		
	SWR	[Max]		2.5 : 1(Typ 2 : 1)		
	Input Impe	dance $[\Omega]$	50 Ohm			
	Polariz	ation		Linear		
	Total Gair	n ( Peak / /	Avg ) [dBi]	1.1 / -4.5		
		<b>T</b> I	Peak	-0.55		
	Azimuth	Theta	Average	-4.85		
		Phi	Peak	1.03		
			Average	-3.84		
		Theta	Peak	-0.00		
Gain[dBi]			Average	-4.50		
	Elevation 1		Peak	0.67		
		Phi	Average	-3.73		
		Theta	Peak	-1.85		
			Average	-5.71		
	Elevation 2		Peak	1.07		
		Phi	Average	-4.87		

Ver 1.0 (2008.04.14) 6 /31 Page



#### 4.2 S11 Graph of Set Condition

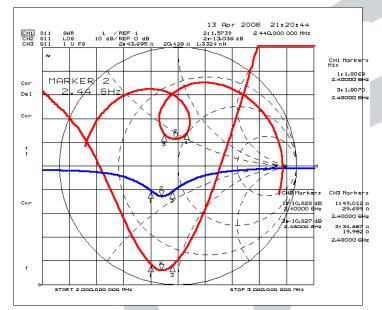


#### 4.3 Test Fixture Condition

ITEM	SPEC		
Frequency Range [MHz]	2400 ~ 2480		
Lower frequency(1860MHz) SWR [Min~Max]	1.5~2.5 : 1(Typ 2.1 : 1)		
Upper frequency(1940MHz) SWR [Min~Max]	1.5~2.5 : 1(Typ 2.1 : 1)		

#### 4.4 S11 Graph of Test Fixture Condition (TD)



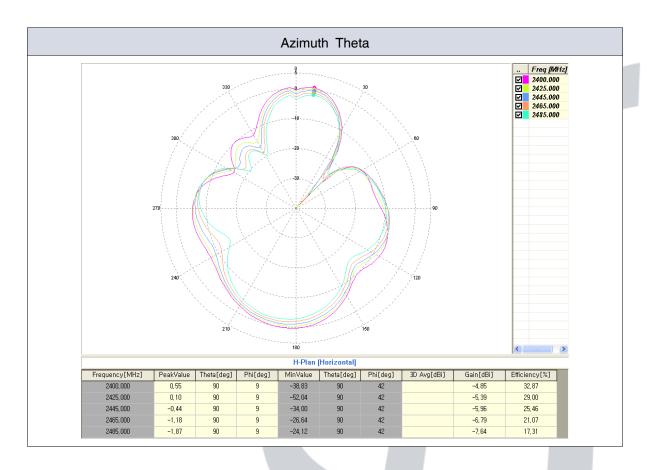


7 /31 Page Ver 1.0 (2008.04.14)



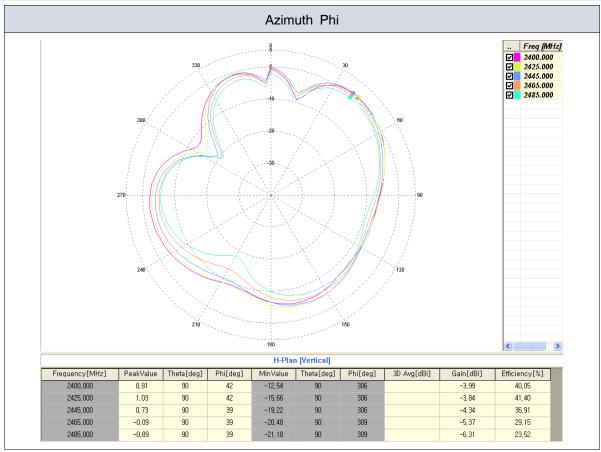
#### 4.5 Radiation Pattern

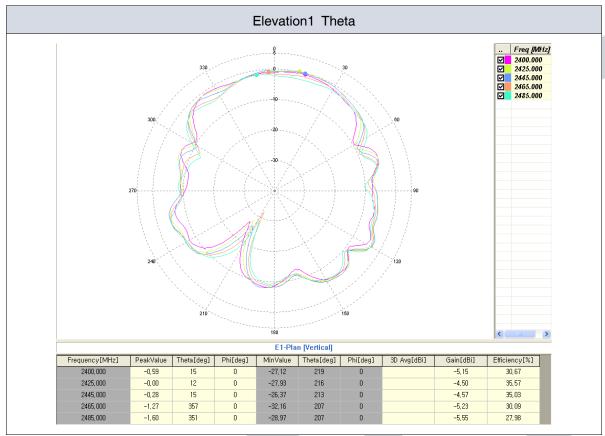
Azimuth Plane	Elevation1 Plane	Elevation2 Plane	
270° 90°	90° 180°	270° — 90° — 90° — 180°	
Theta	Vertical field of	measured plane	
Phi	Horizontal field of measured plane		



Ver 1.0 (2008.04.14) 8 /31 Page

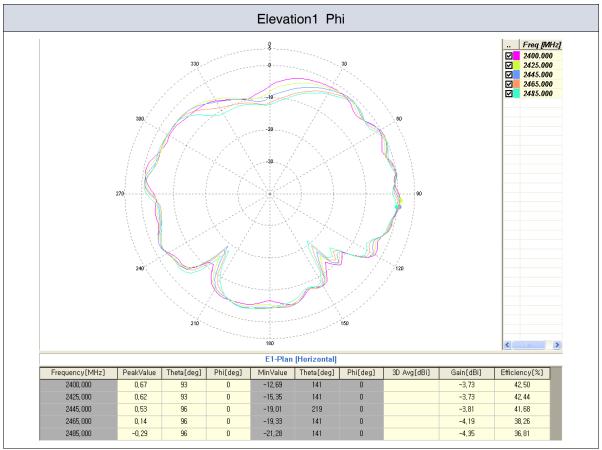


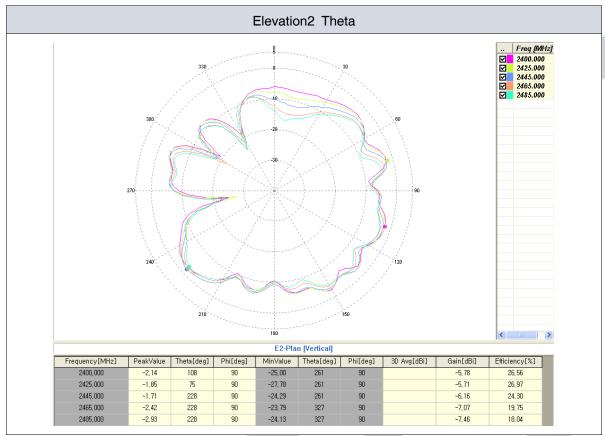




Ver 1.0 (2008.04.14) 9 /31 Page

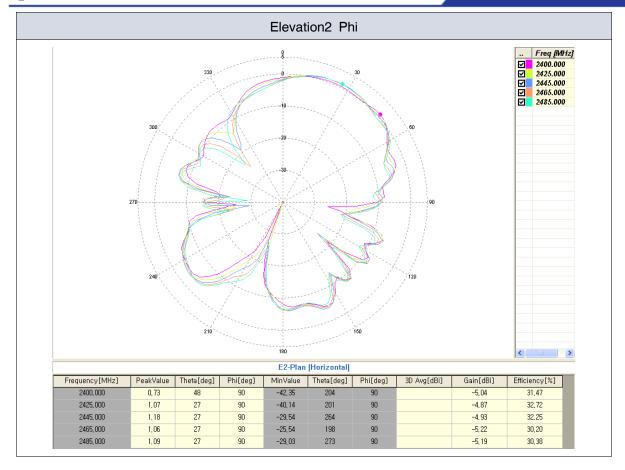






Ver 1.0 (2008.04.14) 10 /31 Page





#### 5. Measurement Process

#### 5.1 SWR/Return loss

Use Network Analyzer when measuring SWR/Return loss and selecting standard SPL, Use automatic inspection equipment when selecting superior and inferior goods.

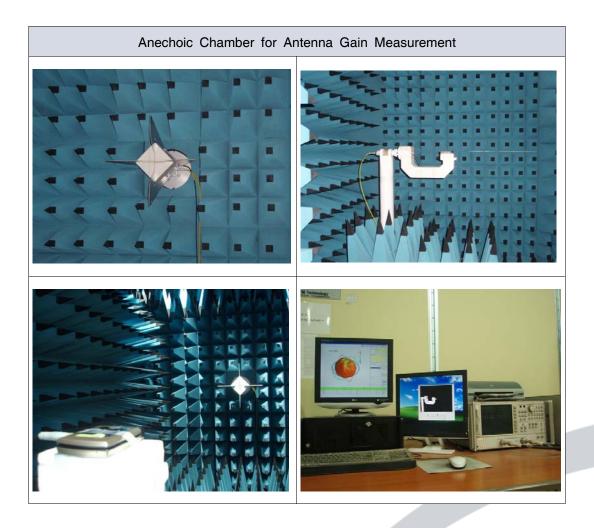
	Set Condition	Test Fixture Condition		
Network Analyzer	Agilent HP8753D	Agilent HP8753D or Advantest R3765CH		
Cable	RF cable(300mm)	RF cable(300mm)		
Test condition		CLLCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCC		

Ver 1.0 (2008.04.14) 11 /31 Page

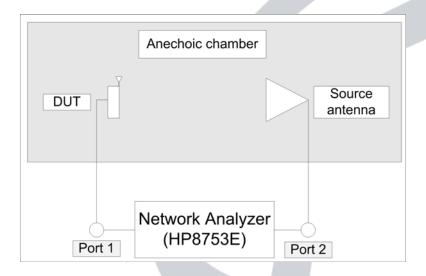


5.2 Gain

Antenna gain is measured in the Anechoic Chamber of this company, using set above of 4.1 list.



#### 5.3 Gain test block diagram

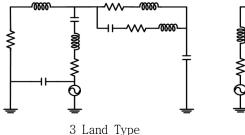


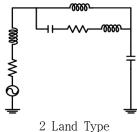
Ver 1.0 (2008.04.14) 12 /31 Page



#### 6. Internal Block Diagram

This product is made of the dielectric block and RF part materialized the characteristics by structural change of Ag pattern on the brick of dielectric block and conditioning value of the structural equivalent circuit.

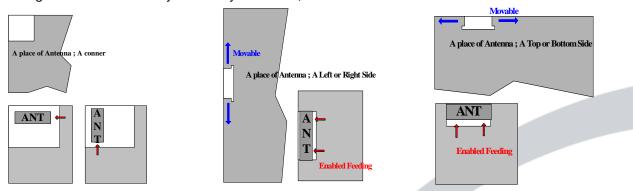




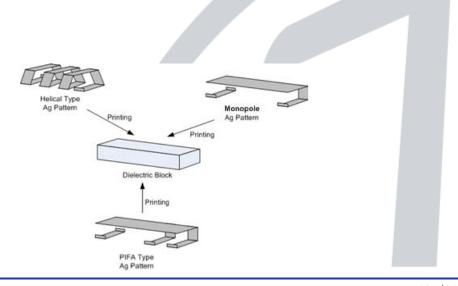
### 7. Basis Action / Application Note

This product is the internal dielectric chip antenna of radio communication, coverts the electric signal advanced along by transmission line into free space wave.

This product will be mounted wherever you want and the design is revised by mount condition. But require attention to select the mount position, because this product is the radiation part and changed characteristics by boundary condition,



As the following, this product is easy to revise the various types for the boundary condition.



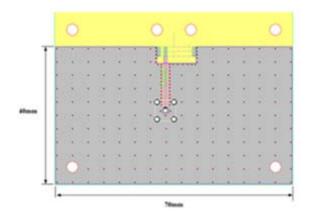
Ver 1.0 (2008.04.14) 13 /31 Page



# 8. Measurement Jig SPEC

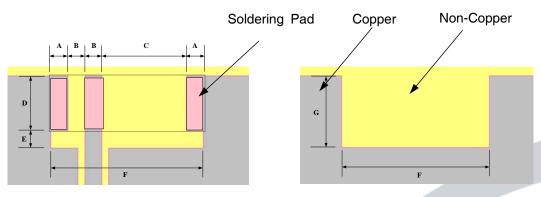
#### 8.1 Test Fixture And GROUND Condition





Test Fixture Loss 0.2~0.3 dB

- Ev B'd and Test Fixture Jig is the same
  - ( Contact way of Ev B'd is soldering, Test Fixture is copper contact way)
- 8.2 PCB Layout & Soldering Pad Dimension



**Top Pattern** 

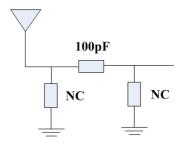
**Bottom Pattern** 

Parameter	Α	В	С	D	E	F	G	Н
Value[mm]	1.1	1.0	1.0	6.0	2.7	1.0	10	3.7

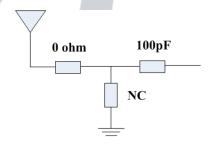
Unit; mm

Unless specified tolerances are ±0.1

#### 8.3 Matching Circuit And Reference Value







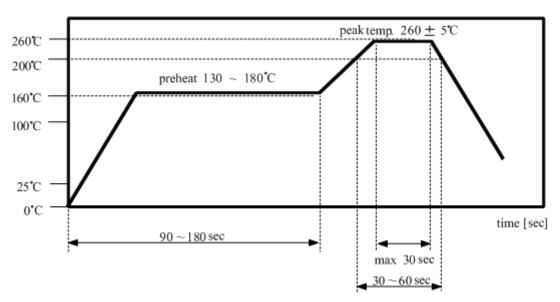
T Matching

Ver 1.0 (2008.04.14) 14 /31 Page



#### 9. REFLOW PROFILE

#### 9.1 Reflow Soldering

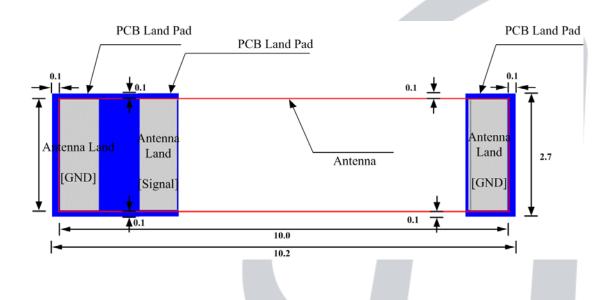


#### 9.2 Manual Soldering

Soldering Temperature :  $340\,^{\circ}\text{C}\pm5\,^{\circ}\text{C}$  , 5sec max per each terminal

#### 9.3 PCB Pattern Design

As the following, the PCB land pattern lays out 0.1mm outside land pattern of antenna more than indicated antenna land dimension



Ver 1.0 (2008.04.14) 15 /31 Page



# 10. Primary Inspection List

Item	Electrical Characteristic[MHz]			Size [mm]	
	VSWR	MAX			
Standard	1860MHz	1940MHz	W=3.0±0.1	L=11.0±0.1	T=1.2±0.1
1	1.86	1.78	2.52	10.01	1.22
2	1.88	1.79	2.53	10.02	1.23
3	1.87	1.83	2.53	10.03	1.23
4	1.88	1.72	2.53	10.01	1.23
5	1.84	1.82	2.52	10.01	1.22
6	1.72	1.81	2.54	10.01	1.24
7	1.85	1.97	2.52	10.02	1.22
8	1.86	1.88	2.53	10.02	1.23
9	1.83	1.86	2.52	10.02	1.21
10	1.81	1.79	2.53	10.02	1.23
11	1.80	1.77	2.53	10.03	1.23
12	1.81	1.88	2.52	10.03	1.22
13	1.79	1.85	2.54	10.02	1.24
14	1.90	1.92	2.52	10.01	1.22
15	1.86	1.89	2.53	10.01	1.23
16	1.86	1.81	2.53	10.02	1.21
17	1.87	1.78	2.52	10.03	1.22
18	2.07	1.93	2.54	10.03	1.24
19	1.87	1.87	2.52	10.01	1.22
20	1.95	1.83	2.52	10.02	1.22
Min	1.72	1.72	2.52	10.01	1.21
Max	2.07	1.97	2.54	10.03	1.24
Х	1.85	1.83	2.52	10.01	1.22
σ	0.06	0.06	0.01	0.01	0.01
Cpk	4.12	4.47	3.28	3.38	2.76
Decision	ok	ok	ok	ok	ok

Ver 1.0 (2008.04.14) 16 /31 Page



# 11. Reliability Condition

#### 11.1 Environment Test

ITEM	TEST CONDITION	LIMIT
High Temperature Action	85℃±3℃, 1hr	
High Temperature Resistance	+85℃±3℃, 120hr±2hr	
Low Temperature Action	-40℃±3℃, 1hr	After test, Must meet the
Low Temperature Resistance	-40℃±3℃, 120hr±2hr	characteristics spec of 4.4 list
Humidity Action	+85±3℃, RH85%	
Humidity Resistance	+85±3℃, RH85%, 120hr±2hr	

#### 11.2 Thermal shock test, Reflow test

ITEM	TEST CONDITION	LIMIT
	condition : -40℃±3℃/1min ↔ +85℃±3℃/1min	
Thermal shock	Test Cycle: 32 cycle	After test, Must meet the
	Temperature change time : within 5 min	characteristics spec of
Deflow	Pre Heating: 200±5℃, 30~60 sec	4.4 list
Reflow	Peak Heating: 260℃±5℃, 30sec Max	

#### 11.3 Mechanical Test

ITEM	TEST CONDITION	LIMIT
Vibration	Freq: 10~500Hz, Acceleration: 10 ×9.8 m/s²(G) Sweep time: 15 min, X.Y.Z each 5 times	After test, Must meet the
Drop	18 times free fall Using the drop jig 152cm high Jig : 120g±20g Plastic Jig Bottom : Concrete or Iron	characteristics spec of 4.4 list

#### 11.4 MSL LEVEL Test

#### 1) JEDEC J-STD-020C Test

	Floor Life		Soak F	Requirements
	Time Conditions		Time	Conditions
1	Unlimited	= < 30°C/85%RH	168+5/-0	= < 85℃/85%RH

#### 2) Test Condition

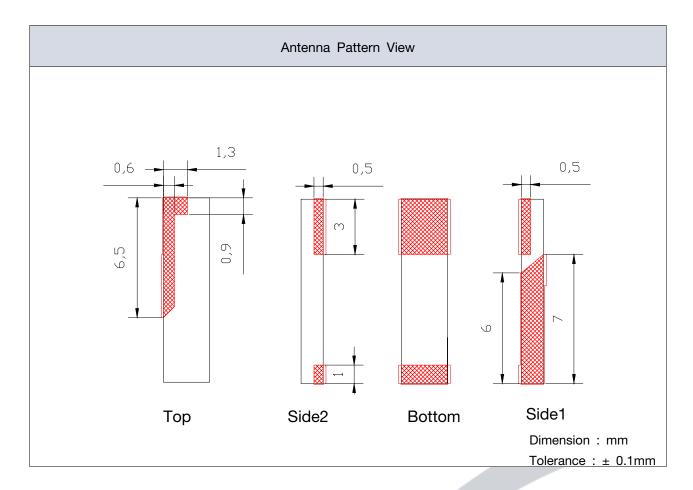
ITEM	Conditon		LIMIT
Soak Requirements	After leaving +85±3℃, RH85% 2 times Reflow without aging	168hr±2hr	After test, Must meet the characteristics spec of 4.4 list

Ver 1.0 (2008.04.14) 17 /31 Page

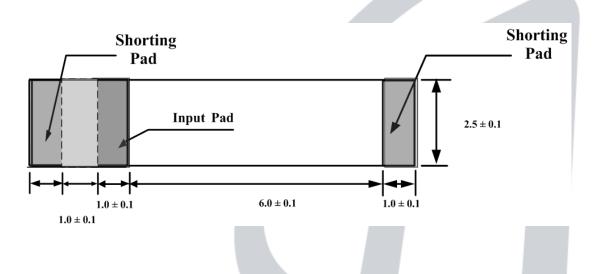


#### 12. Mechanical Characteristics

#### 12.1 Antenna Pattern Dimension



#### 12.2 Pin name



Ver 1.0 (2008.04.14) 18 /31 Page



#### 12.3 Lot number notation

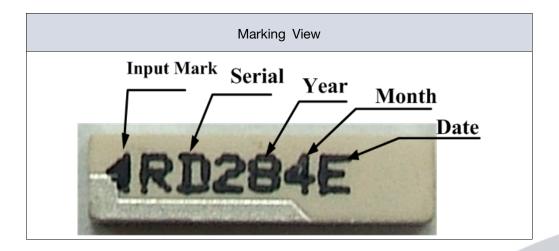
8 4 E 1 2 3

① Year : 7 - 2007 ····

2 Month: 1 - January, 2 - February · · 9 - September, A - October, B - November · ·

③ Date : 1 - 1st , 2 - 2nd ···· A - 10th, B - 11th ····

#### 12.4 Marking



■ RD2 8 4 E
 ① ② ③ ④ ⑤

1 Input Signal

2 Serial

③ Year : 1 - 2001, 2 - 2002, ···· 7 - 2007 ····

4 Month: 1 - January, 2 - February · · 9 - September, A - October, B - November · ·

⑤ Date : 1 - 1st , 2 - 2nd · · · · A - 10th, B - 11th · · · ·

#### 12.5 Marking type

Ink marking - Using Black Ink

Ver 1.0 (2008.04.14) 19 /31 Page

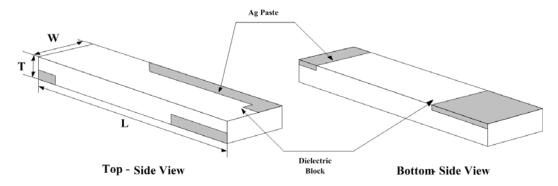


#### 13. Structure and Material

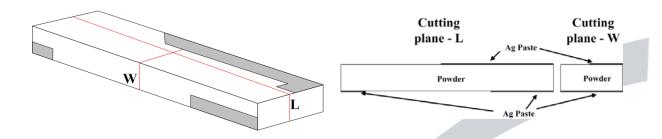
#### 13.1 materialization method

Chip antenna forms the pattern with Ag paste on the brick of dielectric block and materializes the characteristics

#### 13.2 Struture



#### 13.3 Internal cross section



#### 13.4 Material

ITEM	Material	Maker	Printing pattern SPEC
Dielectric Block	Powder	Fuji	
PATTERN	Ag Paste	DAEJOO	Thickness: TYP 10 /m
PAD	Ag paste	DAEJOO	Thickness: Min 10/m (TYP 16~20/m)

Ver 1.0 (2008.04.14) 20 /31 Page



#### 14. Attention

#### 14.1 Temperature Condition

	Range of Temperature	Unit
Application temperature	-40 ~ +85	°C
Keeping temperature	-40 ~ +85	°C

#### 14.2 Temperature Test Condition

	Condition	Range of Temperature
Application temperature	Low	24hr normal action at -75°C
	High	24hr normal action at +150℃
Keeping temperature	Low	normal action when left for 1000hr at -75℃
	High	normal action when left for 1000hr at +85℃



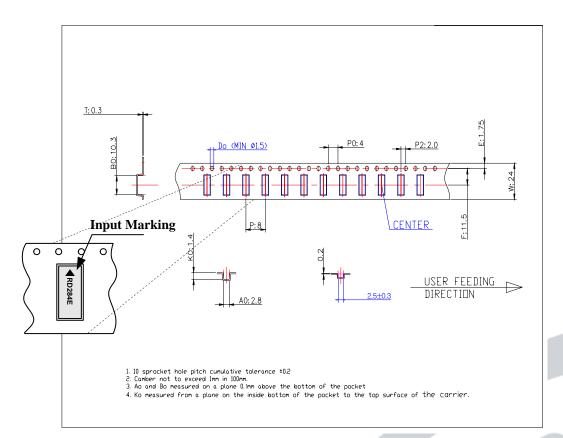
Ver 1.0 (2008.04.14) 21 /31 Page



#### 15. Packing

#### 15.1 Carrier/Reel

ITEM	Material	Surface Resistance	electrostatic emission	Packing method
Carrier tape	A-PET	Typical 10°Ω	10V MAX	Heat muses
Cover tape	PET	Typical 10°Ω	30V MAX	Heat press
Reel	PS	Typical 10°Ω	30V MAX	-

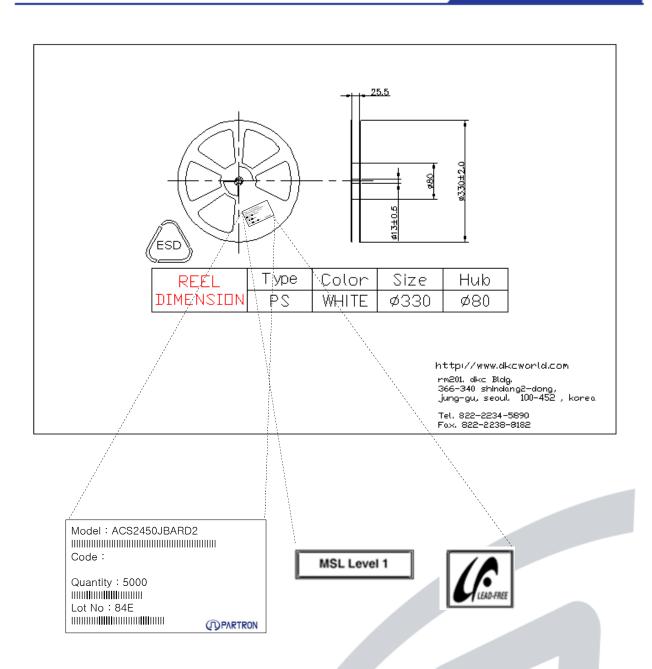


DKC DWG. No	١,	D-2408-005
DIMENSIONAL UNIT		ММ
UNTOLERANCE DIMENSION	UNTOLERANCED DIMENSION	
CAD FILE NA	ME	041211
DESIGNED BY	,	K. M. C
SCALE		1/1
CARRIER TAPE 2.5*10*1.2P		
PART.	PART. CAR	
MATERIAL		A-PET
LENGTH		49.2M
COUNT		6150P

NAME	SPEC.
V	24.0±0.2
E	1.75±0.1
F	11.5±0.1
Do	1.5+0.1
Р	8.0±0.1
Po	4.0±0.1
P2	2.0±0.1
Ao	2.8±0.1
Во	10.3±0.1
Ko	1.4±0.1
Т	0.3±0.05

Ver 1.0 (2008.04.14) 22 /31 Page

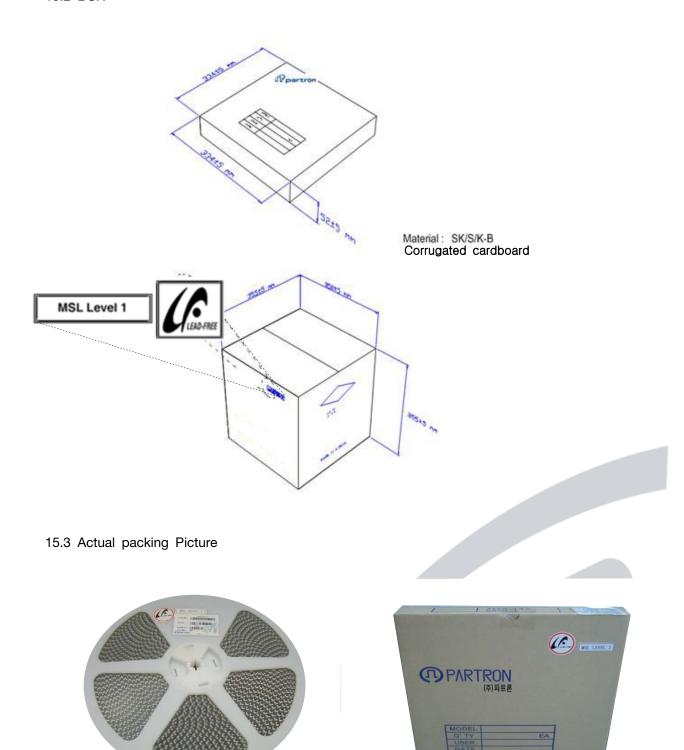




Ver 1.0 (2008.04.14) 23 /31 Page



#### 15.2 BOX



Internal Box

Ree1

Ver 1.0 (2008.04.14) 24 /31 Page





External Box



FROM
PARTRON.CO.LTD
SEOKWOO.DONG 22-6
HWASEONG - SI
GYEONGGI - DO
445-170.KOREA

CODE NO:

MODEL: ACS2450JBARD2

QUANTITY: 30000

DATE: 2008/04/02

LOT NO: 84E

CHIP ANT

Reel / Internal Box label

External Box label

Pertron



Ver 1.0 (2008.04.14) 25 /31 Page



#### 16. Process Control

Product			I	ssued/Revisio	on	Process Control					By designed	By check	ked By	approved		
СН	CHIP ANTENNA			ed 04.04 ed 05.04							11					
Input	FLOW CHART		Process		Management of Factors						Management of quality					
Materials			name	Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action		
Ceramic POWDER		$\Diamond$	Import Inspectio	1					shrinking rate permittivity	refer to Guide Sheet	Micrometer Network	10ea/L0T	C/sheet	Return		
POWDER lubricant			powder	Mixer					mixing	POWDER lubricant	Scale	PER MIXING	-	Exhaust		
			Shaping	Press	pressure Mold Conditio		Per LOT 1/day	parameter C/SHEET	dimension weight density aspect	refer to Guide Sheet	Micrometer scale Calculated Visual	5/100EA 10ea/lot	LOT CARD	Exhaust		
			Plasticit	/ Plasticity Hole	SETTER Outsic Temperature PROFILE	ratar to	all 2/day 1/month	C/sheet								
		$\Diamond$	Block						wide length shape	refer to Guide Sheet	Micrometer Calipers Visual Inspection	20ea/L0T 20ea/L0T all	C/sheet	Exhaust		
AG PASTE			SIDE1 PAD Printing	Printer screen	Squeeze velocity/prest SNAP	refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework		
			Dry	Dryer Dry Jig	Temperatu Belt spee	0	1/week	Parameter	Dry Condition  Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework		

Ver 1.0 (2008.04.14) 26 /31 Page





	Produc	t	I	ssued/Revision	า					Record	By designed	By chec	ked By	approved		
СНІ	CHIP ANTENNA			ed 04.04. ed 05.04.		Process Control					01					
Input	FLOW CHART		Process		Manag	Management of Factors				Management of quality						
Materials	prepar ation	Main Process	name	Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action		
AG PASTE			SIDE 2 PAD Printing	Printer screen	Squeeze velocity/presur SNAP	e refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework		
			Dry	Dryer Dry Jig	Temperatur Belt speed	0	1/week	Parameter	Dry Condition  Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework		
			Baking	Baking Hole mesh net	Temperatur Belt speed		1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot card	Exhaust Rework		
AG PASTE			TOP printing	Printer screen	Squeeze velocity/presur SNAP	refer to Guide Sheet	1/day	_	PATTERN dimension	refer to Guide Sheet	measure	10ea/3Jig	c/sheet	Rework		
			Dry	Dryer Dry Jig	Temperatur Belt speed	0	1/week	Parameter	Dry Condition  Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework		
AG PASTE			BOTTOM PAD Printing CTQ	printer screen	Squeeze velocity/presur SNAP	e refer to Guide Sheet	1/day	-	PATTERN dimension aspect	refer to Guide Sheet	measure Microscope	10ea/3Jig	c/sheet	Rework		

Ver 1.0 (2008.04.14) 27 /31 Page





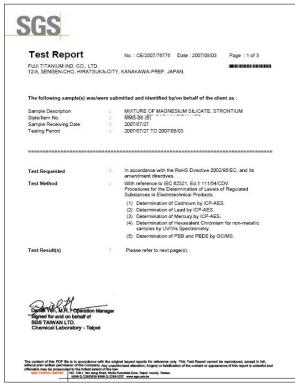
Product			Issued	sued/Revision						Record	Ву	/ designed	By chec	ked By	approved	
СН	CHIP ANTENNA			d 04.04. d 05.04.		Process Control					PRCP-C00					
Input	FLOW	CHART	Process		M	Management of Factors			Management of quality							
Materials	prepar ation	Main Process	name	Equipment Name	Checked		Condition	Cycle of management	Record	Checked Item	Margin		hod of pection	Cycle of management	Record	Action
			Dry	Dryer Dry Jig	Temperature Belt speed		refer to Guide Sheet	1/week   Parameter		Inspection	all	Lot card	Rework			
			Baking	Baking Hole mesh net	proofreading		refer to Guide Sheet	1/week Par C/	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection		all	Lot card	Exhaust Rework
		$\Diamond$	aspect inspection							aspect	Reference SPL refer to Guide Sheet		Inspection OSCOPE	all	Lot card	Exhaust repair
			MARKING	Marking Machine						marking	Reference SPL	Visual	Inspection	all	Lot card production diary	Rework Exhaust
		$\Diamond$	Electrical Characteristic	NETWORK Inspection Jig			refer to Guide Sheet	1/2hour	C/sheet	Electrical Characteristic	refer to Guide Sheet	Ne	twork	all	Lot card production diary	Exhaust repair
		$\Diamond$	aspect inspection							aspect dimension	Reference SPL refer to Guide Sheet		Inspection oscope	all	Lot card production diary	Exhaust repair
Carrier cover reel			Taping							Quantity Direction aspect	refer to Guide Sheet	Ма	ınual	all	Lot card production diary	Rework
		$\Diamond$	shipper inspection	NETWORK Inspection Jig	proofreading Condition		refer to Guide Sheet	1/person	C/sheet	Electrical Characteristic aspect packing	refer to Guide Sheet	micr	twork oscope Inspection	refer to Guide Sheet	Result Paper	return Exhaust
packing box label			packing	bar code printer						packing P/N Quantity	refer to Guide Sheet	Visual	Inspection	all	-	Rework
		$\Diamond$	packing inspection							packing P/N Quantity	refer to Guide Sheet	Visual	Inspection	all	_	return

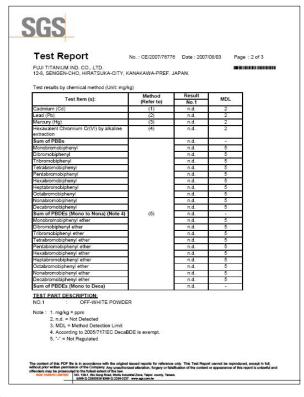
Ver 1.0 (2008.04.14) 28 /31 Page

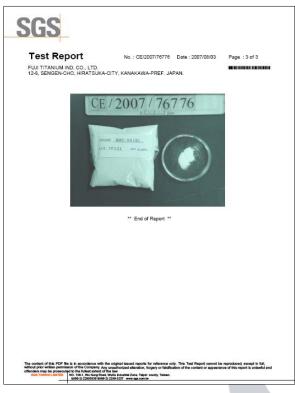


#### 17. 유해물질 성적서

#### 1) Ceramic Powder



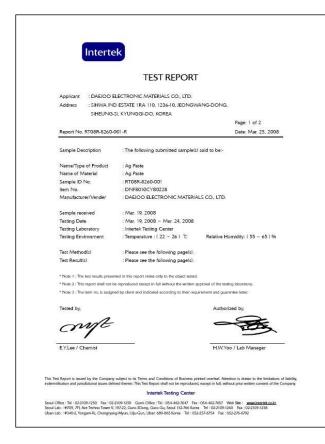




29 /31 Page



#### 2) Ag Paste





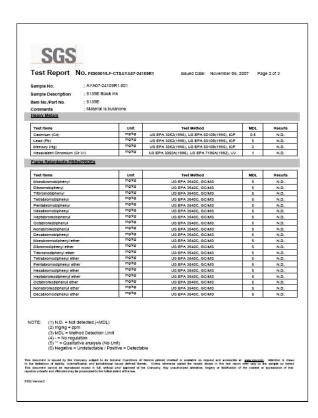


Ver 1.0 (2008.04.14) 30 /31 Page



#### 3) Marking Ink









31 /31 Page